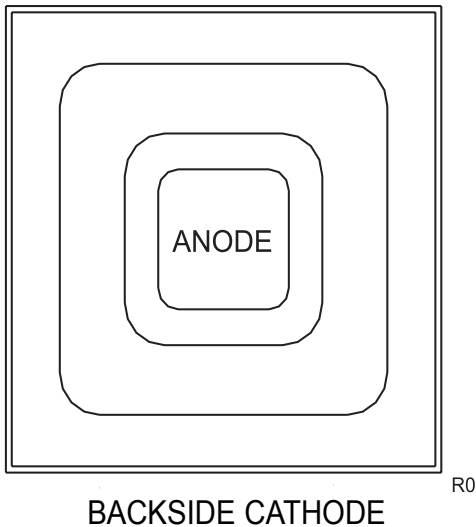


PROCESS DETAILS

Process	EPITAXIAL PLANAR
Die Size	11 x 11 MILS
Die Thickness	11 MILS
Anode Bonding pad Area	3.3 x 3.3 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 18,000Å

GEOMETRY



GROSS DIE PER 4 INCH WAFER

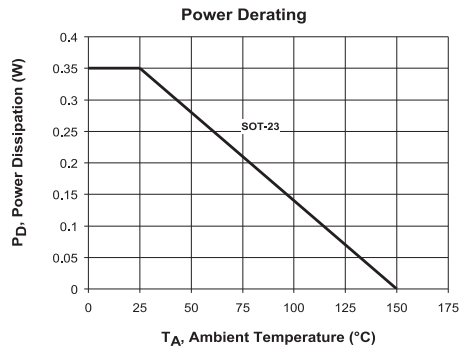
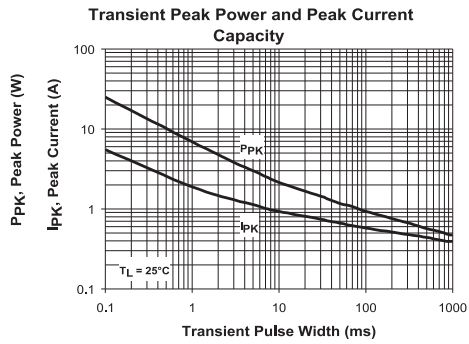
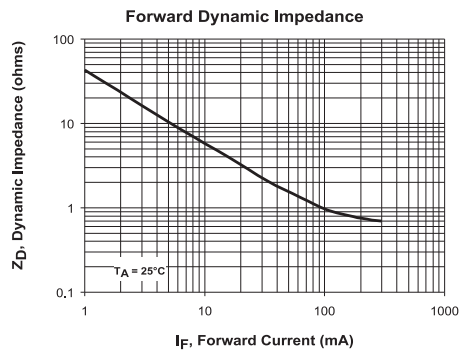
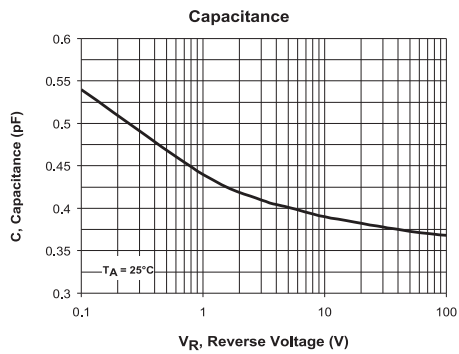
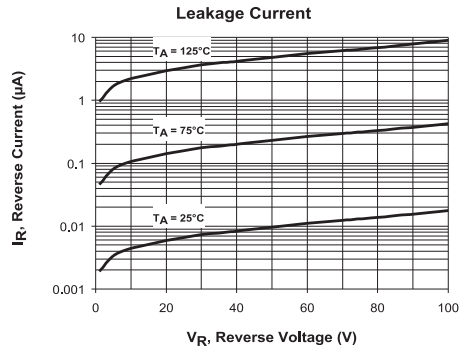
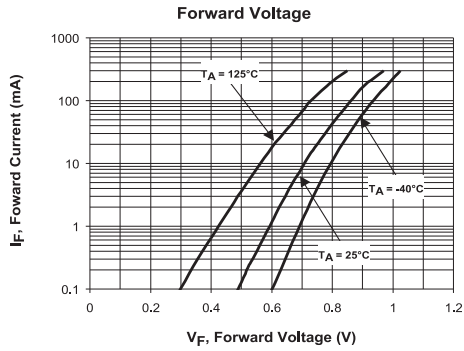
94,130

PRINCIPAL DEVICE TYPES

CMPD914
CMPD4448
1N914
1N914B
1N4148
1N4448
1N4154
1N4454

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